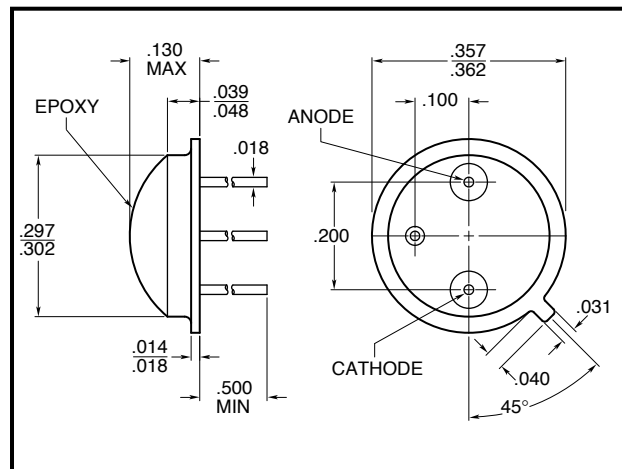


**FEATURES**

- High power output
- Standard 3-lead TO-39 hermetic package
- Chip size .050 x .050 inches
- Case isolated
- All metal surfaces gold plated

ELECTRO-OPTICAL CHARACTERISTICS AT 25°C

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Total Power Output, P_o	$I_F = 300\text{mA}$	28	31		mW
Peak Emission Wavelength, λ_p	$I_F = 50\text{mA}$	462	470	475	nm
Spectral Bandwidth at 50%, $\Delta\lambda$			40		nm
Half Intensity Beam Angle, θ			110		Deg
Forward Voltage, V_F	$I_F = 300\text{mA}$		3.6	4	Volts
Reverse Breakdown Voltage, V_R	$I_R = 10\mu\text{A}$	2	5		Volts

ABSOLUTE MAXIMUM RATINGS AT 25°C CASE

Power Dissipation ¹	1200mW
Continuous Forward Current ¹	300mA
Reverse Voltage	2V
Lead Soldering Temperature (1/16" from case for 10sec)	240°C

¹Derate per appropriate thermal dissipation value above 25°C.

THERMAL PARAMETERS

Storage and Operating Temperature Range	-40°C TO 100°C
Maximum Junction Temperature	100°C
Thermal Dissipation Junction-Case	75°C/W Typical
Thermal Dissipation Junction-Air	145°C/W Typical

